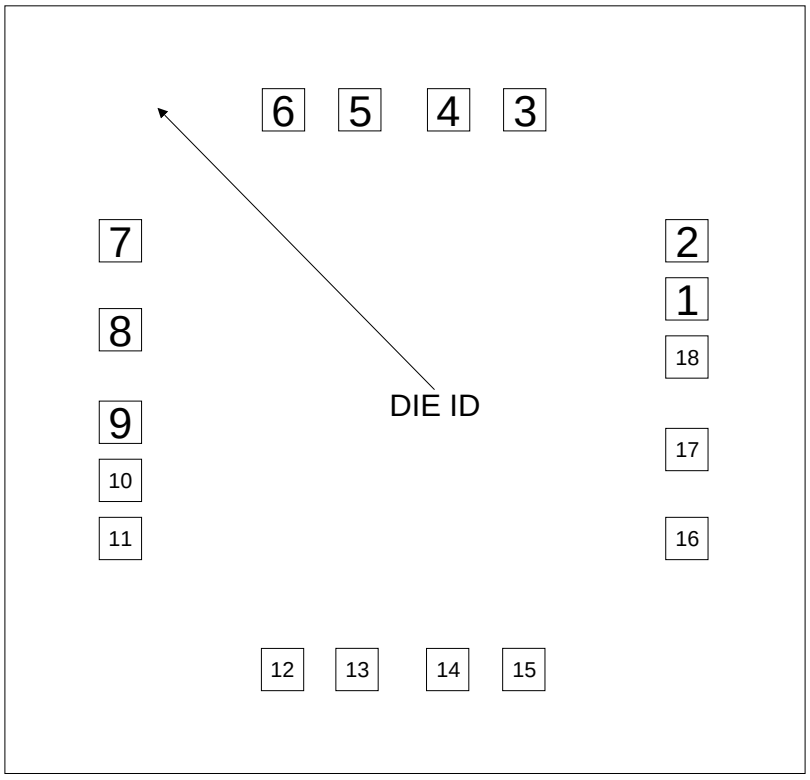
DS90LV032A MDS (PRELIMINARY)
3V LVDS QUAD CMOS DIFFERENTIAL LINE RECEIVER

6-Jan-2011

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	DS90LV032A	Bond Pad Opening Size (min)	81.85µm x 81.76µm
Die Step	A	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX SOG NITRIDE
Wafer Diameter	203.2mm	Back Side Metal	BAREBACK
Die Size (Drawn)	1548.892µm x 1486.154µm 61.0mils x 58.5mils	Back Side Connection	Floating
Thickness	406.4µm Nominal		
Min Pitch	112.50µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(A-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
RIN 1-	1	545.67	175.72	81.90	x	81.90
RIN 1+	2	545.67	288.23	81.90	x	81.90
ROUT 1	3	231.77	541.78	81.86	x	81.77
EN	4	84.42	541.71	81.90	x	81.90
ROUT 2	5	-87.46	541.78	81.86	x	81.77
RIN 2+	6	-235.22	541.71	81.90	x	81.90
RIN 2-	7	-550.89	288.23	81.90	x	81.90
GND	8	-550.89	116.01	81.90	x	81.90
GND	9	-550.89	-63.09	81.90	x	81.90
RIN 3-	10	-550.89	-175.59	81.90	x	81.90
RIN 3+	11	-550.89	-288.09	81.90	x	81.90
ROUT 3	12	-237.04	-541.78	81.86	x	81.77
EN*	13	-92.88	-541.71	81.90	x	81.90
ROUT 4	14	82.60	-541.78	81.86	x	81.77
RIN 4+	15	230.00	-541.71	81.90	x	81.90
RIN 4-	16	545.67	-288.09	81.90	x	81.90
VCC	17	545.67	-115.88	81.90	x	81.90
VCC	18	545.67	63.23	81.90	x	81.90

Notes

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